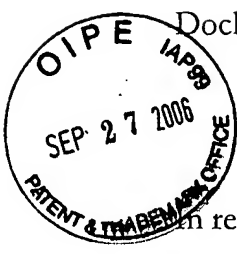


SRW



Docket No.: INTEL-0069

PATENT

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of

Confirmation No.: 2131

Edward R. HURLEY et al.

Group Art Unit: 1725

Serial No.: 10/806,118

Examiner: R. Beveridge

Filed: March 23, 2004

Customer No.: 34610

For: METALLIC SOLDER THERMAL INTERFACE MATERIAL LAYER AND
APPLICATION OF THE SAME

SUBSTANCE OF THE INTERVIEW

U.S. Patent and Trademark Office
Customer Service Window
Randolph Building
401 Dulany Street
Alexandria, Virginia 22314

Sir:

Applicants conducted a personal interview on September 19, 2006. Applicants gratefully acknowledge courtesies extended by Examiner Rachel Beveridge and Examiner Johnson during the personal interview.

During the personal interview, applicants argued that the outstanding rejection was improper at least because there was no motivation to combine the references as alleged in the Office Action.

Applicants respectfully submit that the references, either alone or in combination, do not teach or suggest the feature of providing at least the thermal interface material in a vacuum chamber under vacuum conditions and heating the thermal interface material in the vacuum

chamber to form liquid metallic solder, as recited in independent claim 1. That is, neither Sreeram nor Totino relates to this feature. For example, Sreeram does not teach or suggest features relating to a vacuum chamber, vacuum conditions and/or heating in the vacuum chamber. Additionally, Totino does not relate to a thermal interface material. For at least these reasons, applicants asserted that independent claim 1 defines patentable subject matter.

Additionally, applicants asserted that each of independent claims 15 and 31 included specific features relating to a vacuum chamber, vacuum conditions, heating, pressurizing and/or an inert atmosphere. It is respectfully submitted that none of the applied references teach or suggest all the features of each of independent claims 15 and 31.

Examiner Johnson indicated that if a next Office Action were issued, the next Office Action would be a non-Final Office Action.

It is respectfully submitted that this paper serves as a Substance of the Interview.

Please charge any shortage in fees due in connection with the filing of this, concurrent and future replies, including extension of time fees, to Deposit Account 16-0607 and please credit any excess fees to such deposit account.

Respectfully submitted,
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Date: September 27, 2006